

Title (en)

Dot matrix application of adhesive for blister and skin packaging.

Title (de)

Verwendung von Klebstoff in Punktmatrix für Blister- oder Skin-Verpackungen.

Title (fr)

Application en forme d'une matrice de points d'un adhésif pour emballages du type blister ou sous peau.

Publication

**EP 0642988 A1 19950315 (EN)**

Application

**EP 93307234 A 19930914**

Priority

EP 93307234 A 19930914

Abstract (en)

A Dot-Matrix system of adhesive application which will apply dots of adhesive to substrate material 16 to cause "Blister" packing enclosure 15 to adhere to the substrate material 16 along flanges 17. The flanges 17 can either be pressed on to the substrate 16 or drawn against it by vacuum. Various forms of substrate material can be used including cardboard, rigid or semi-rigid plastic, screen printed silk or any other relatively porous material. Application of the adhesive may be by the stylus of flexographic apparatus, lithoplate roller of lithographic processes or the roller in the Gravure printing process. The Dot-Matrix system of adhesive application will reduce the quantity of adhesive needed to secure a bond between the packaging film and the substrate material and such reduction in adhesive enables the film packaging to be manually moved from the substrate relatively easily. <IMAGE>

IPC 1-7

**B65D 75/36**; **B65B 51/02**

IPC 8 full level

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CPC (source: EP)

**B65B 51/026** (2013.01); **B65D 75/305** (2013.01); **B65D 75/36** (2013.01); **B65D 75/366** (2013.01)

Citation (search report)

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